### SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520SECK03

Super Bright Orange

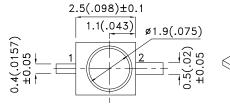
#### Features

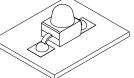
- Subminiature package.
- Gull wing lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

#### Description

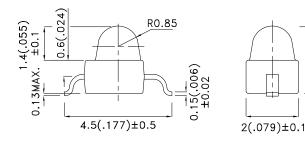
The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

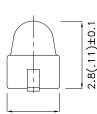
#### **Package Dimensions**





10 -17--0 2





#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.
  The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAA4121 APPROVED: WYNEC

REV NO: V.8 **CHECKED:** Allen Liu DATE: MAR/31/2009 DRAWN: X.M.He



| Selection Guide |                               |             |                        |      |                      |  |  |  |  |  |
|-----------------|-------------------------------|-------------|------------------------|------|----------------------|--|--|--|--|--|
| Part No.        | Dice                          | Lens Type   | lv (mcd) [2]<br>@ 20mA |      | Viewing<br>Angle [1] |  |  |  |  |  |
|                 |                               |             | Min.                   | Тур. | 201/2                |  |  |  |  |  |
| AM2520SECK03    | Super Bright Orange (AlGaInP) | WATER CLEAR | 900                    | 1800 | 20°                  |  |  |  |  |  |

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

2. Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter                | Device              | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|---------------------|------|------|-------|-----------------|
| λpeak  | Peak Wavelength          | Super Bright Orange | 610  |      | nm    | l⊧=20mA         |
| λD [1] | Dominant Wavelength      | Super Bright Orange | 601  |      | nm    | l⊧=20mA         |
| Δλ1/2  | Spectral Line Half-width | Super Bright Orange | 29   |      | nm    | l⊧=20mA         |
| С      | Capacitance              | Super Bright Orange | 15   |      | pF    | VF=0V;f=1MHz    |
| VF [2] | Forward Voltage          | Super Bright Orange | 2.1  | 2.5  | V     | l⊧=20mA         |
| lr     | Reverse Current          | Super Bright Orange |      | 10   | uA    | VR=5V           |

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

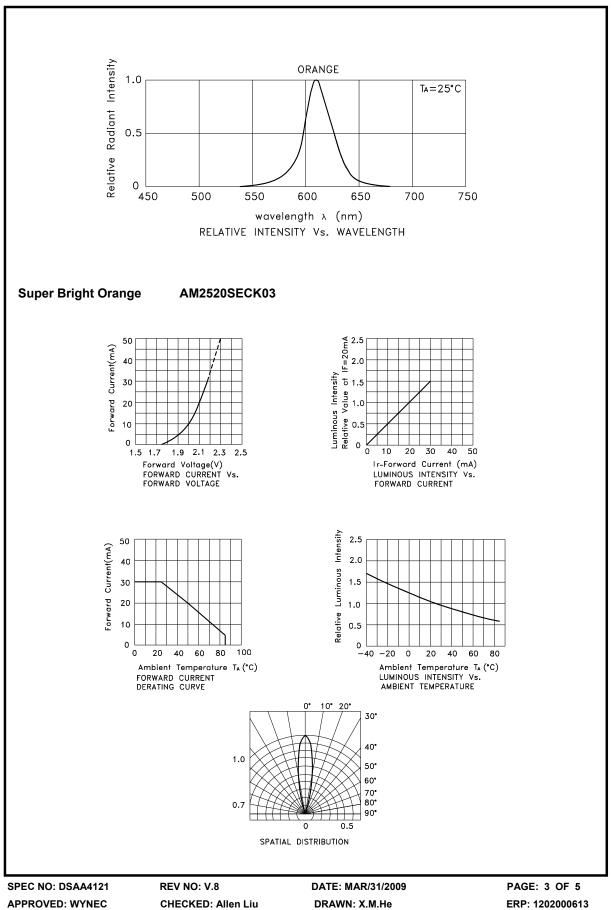
| Parameter                | Super Bright Orange | Units |  |
|--------------------------|---------------------|-------|--|
| Power dissipation        | 75                  | mW    |  |
| DC Forward Current       | 30                  | mA    |  |
| Peak Forward Current [1] | 195                 | mA    |  |
| Reverse Voltage          | 5                   | V     |  |
| Operating Temperature    | -40°C To +85°C      |       |  |
| Storage Temperature      | -40°C To +85°C      |       |  |

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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### AM2520SECK03

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process. 300 (°C) 10 s max 260°C max 250 230°C 4°C/s 4°C/s max 200 150~180°<u>C</u> 4°C/s 150 Temperature 60~120 30~50s 100 50 25°C 0 0 50 100 150 200 250 300 (sec) Time Time \_\_\_\_\_ NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less. Recommended **Soldering Pattern** 1.5 1.6 3.0 1.6 **Tape Dimensions** (Units : mm) TAPE 4.0±0.05 1.75±0.1 2±0.05 4.0±0.1 ø1.5 +0.1 0.3±0.05 3.05±0.1  $5.5\pm0.05$ 5 MAX. 12±0.2 5.3±0.1 5'MAX. Å 2.7±0.1 5'MAX. 5 MAX. 0.8±0.1 2.2±0.1 A-A SECTION

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